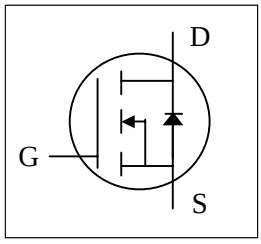
XP10N011LJ

Halogen-Free Product

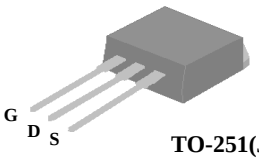
N-CHANNEL ENHANCEMENT MODE

POWER MOSFET

- **100% R_g & UIS Test**
- **Simple Drive Requirement**
- **Lower On-resistance**
- **RoHS Compliant & Halogen-Free**



BV_{DSS}	100V
$R_{DS(ON)}$	11mΩ
I_D	48.4A



TO-251(J)

Description

XP10N011 series are innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

The straight lead version TO-251 package is widely preferred for all commercial-industrial through hole applications.

Absolute Maximum Ratings@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_C=25℃	Drain Current, V_{GS} @ 10V	48.4	A
I_D@T_C=100℃	Drain Current, V_{GS} @ 10V	30.6	A
I_{DM}	Pulsed Drain Current[1]	160	A
P_D@T_C=25℃	Total Power Dissipation	50	W
P_D@T_A=25℃	Total Power Dissipation	1.13	W
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Maximum Thermal Resistance, Junction-case	2.5	℃/W
Rthj-a	Maximum Thermal Resistance, Junction-ambient	110	℃/W

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250uA	100	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V, I_D=30A	-	-	11	mΩ
		V_{GS}=5V, I_D=10A	-	-	16.5	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250uA	1.4	-	3	V
g_{fs}	Forward Transconductance	V_{DS}=5V, I_D=30A	-	50	-	S
I_{DSS}	Drain-Source Leakage Current	V_{DS}=80V, V_{GS}=0V	-	-	25	uA
I_{GSS}	Gate-Source Leakage	V_{GS}=±20V, V_{DS}=0V	-	-	±0.1	uA
Q_g	Total Gate Charge	I_D=30A	-	28	44.8	nC
Q_{gs}	Gate-Source Charge	V_{DS}=50V	-	5	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	V_{GS}=10V	-	11	-	nC
$t_{d(on)}$	Turn-on Delay Time	V_{DS}=50V	-	8	-	ns
t_r	Rise Time	I_D=30A	-	46	-	ns
$t_{d(off)}$	Turn-off Delay Time	R_G=7.5Ω	-	30	-	ns
t_f	Fall Time	V_{GS}=10V	-	103	-	ns
C_{iss}	Input Capacitance	V_{GS}=0V	-	1200	1920	pF
C_{oss}	Output Capacitance	V_{DS}=80V	-	230	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	15	-	pF
R_g	Gate Resistance	f=1.0MHz	-	1.5	3	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage[2]	I_S=30A, V_{GS}=0V	-	-	1.3	V
t_{rr}	Reverse Recovery Time	I_S=30A, V_{GS}=0V	-	50	-	ns
Q_{rr}	Reverse Recovery Charge	dI/dt=100A/μs	-	51	-	nC

Notes:

1.Pulse width limited by Max. junction temperature.

2.Pulse test

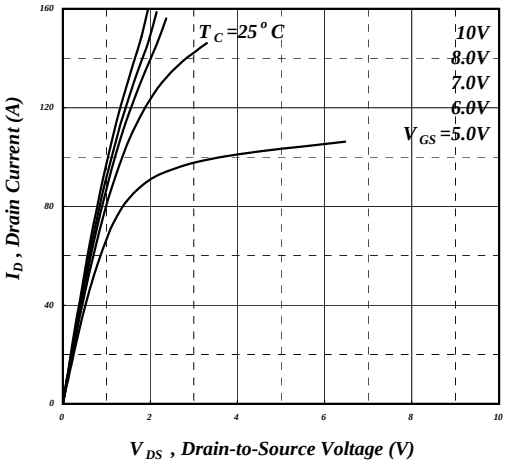


Fig 1. Typical Output Characteristics

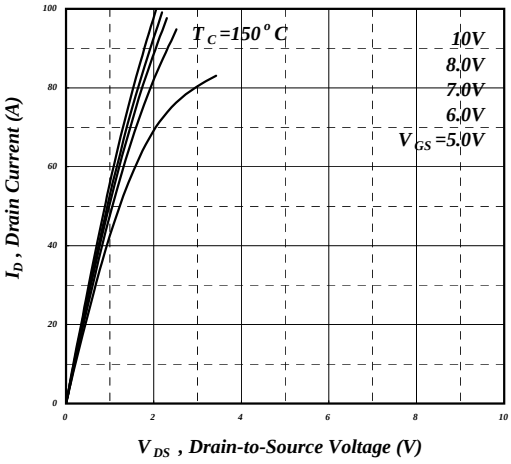


Fig 2. Typical Output Characteristics

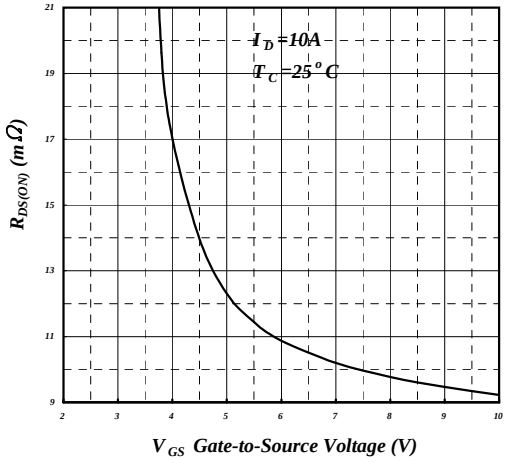


Fig 3. On-Resistance v.s. Gate Voltage

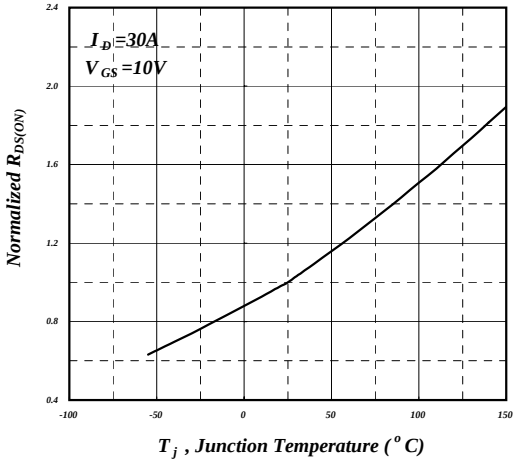


Fig 4. Normalized On-Resistance v.s. Junction Temperature

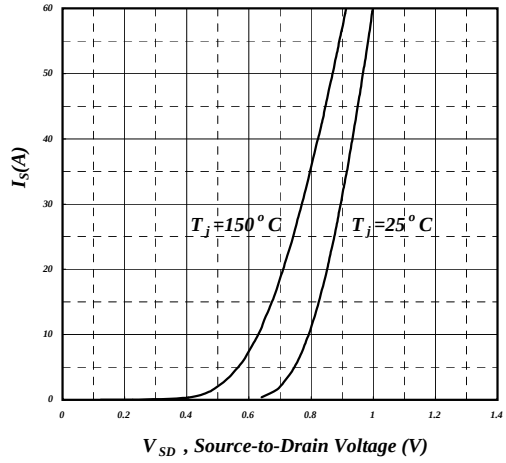


Fig 5. Forward Characteristic of Reverse Diode

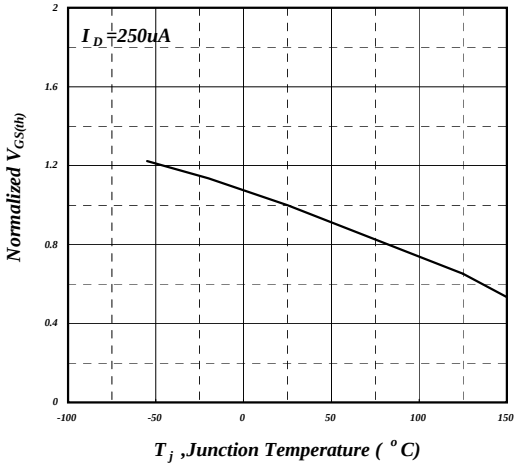


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

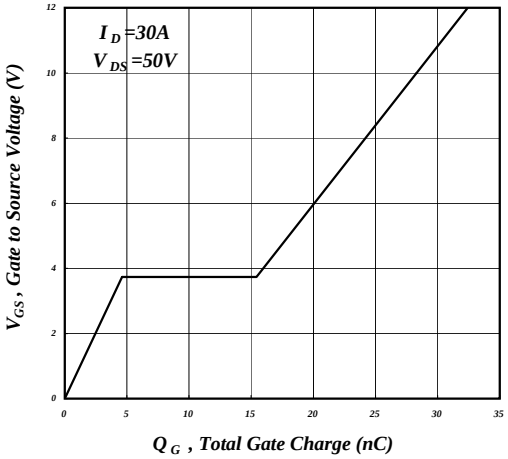


Fig 7. Gate Charge Characteristics

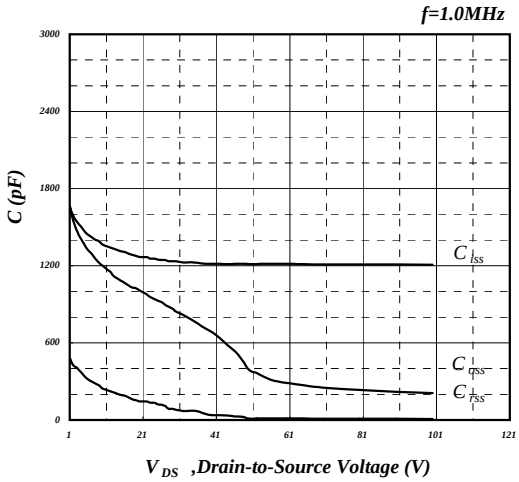


Fig 8. Typical Capacitance Characteristics

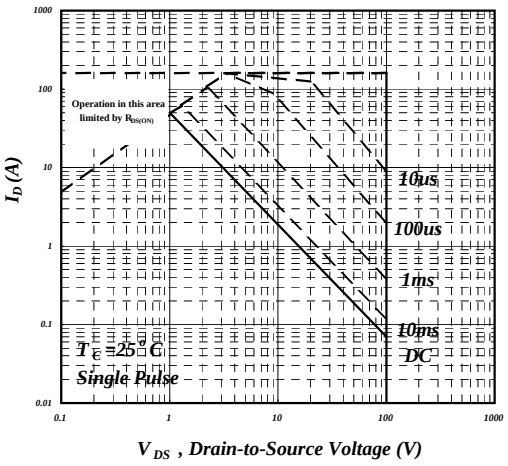


Fig 9. Maximum Safe Operating Area

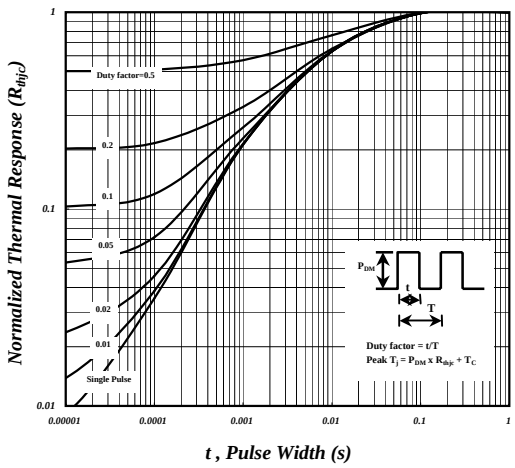


Fig 10. Effective Transient Thermal Impedance

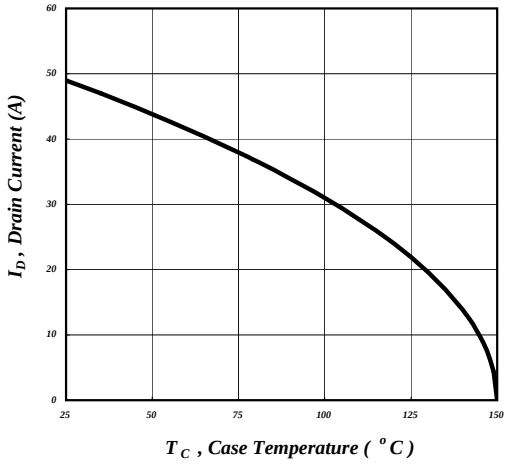


Fig 11. Drain Current v.s. Case Temperature

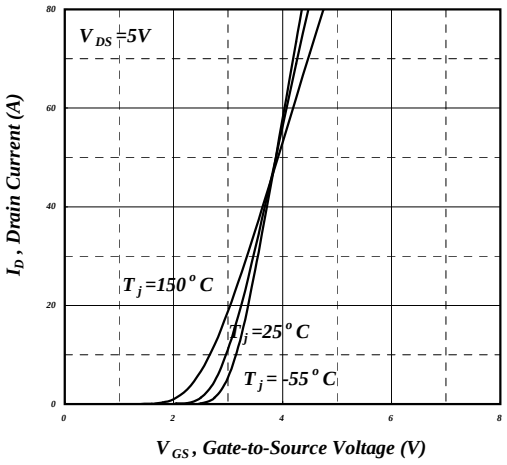


Fig 12. Transfer Characteristics

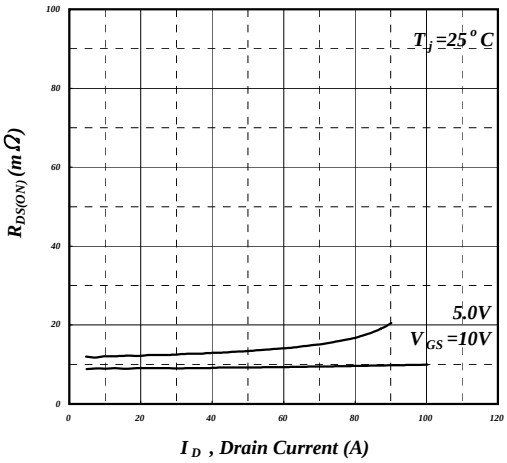


Fig 13. Typ. Drain-Source on State Resistance

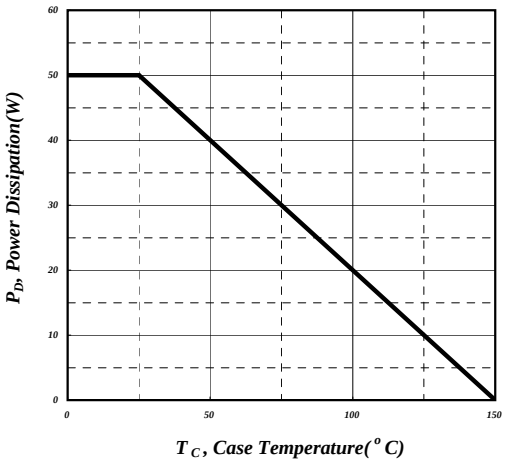
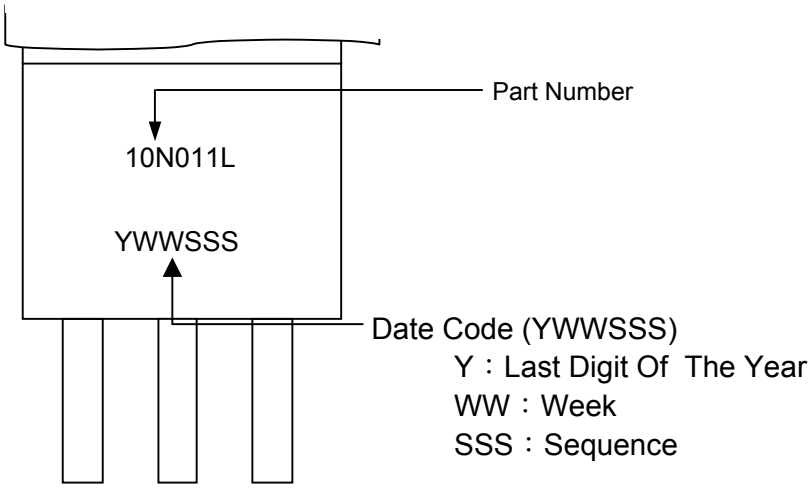
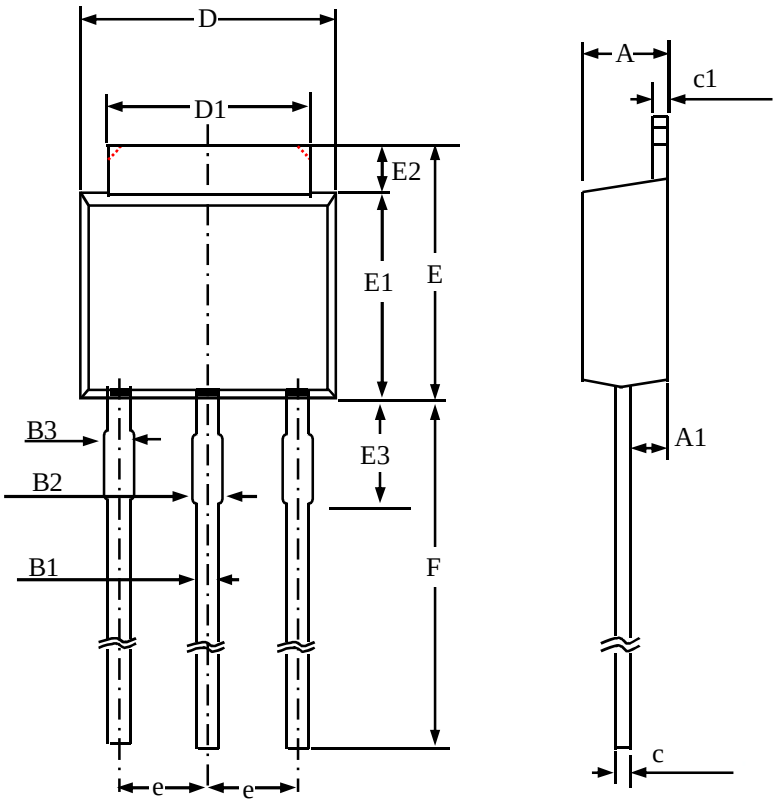


Fig 14. Total Power Dissipation

MARKING INFORMATION



Package Outline : TO-251



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	2.10	2.30	2.50
A1	0.80	1.15	1.50
B1	0.40	0.70	1.00
B2	0.60	0.88	1.15
B3	0.50	0.83	1.15
c	0.30	0.50	0.70
c1	0.30	0.50	0.70
D	6.30	6.55	6.80
D1	4.80	5.20	5.60
E	6.70	7.10	7.50
E1	5.30	5.80	6.30
E2	0.50	1.10	1.70
E3	1.30	1.80	2.30
e	----	2.30	----
F	7.00	8.33	9.65

1.All Dimensions Are in Millimeters.

2.Dimension Does Not Include Mold Protrusions.

Draw No. M1-J3-G-v05-1

TO-251 FOOTPRINT：